

Title (en)
PANEL PRODUCTION DEVICE AND PANEL PRODUCTION METHOD

Title (de)
PLATTENHERSTELLUNGSVORRICHTUNG UND PLATTENHERSTELLUNGSVERFAHREN

Title (fr)
DISPOSITIF ET PROCÉDÉ DE PRODUCTION DE PANNEAU

Publication
EP 4306308 A1 20240117 (EN)

Application
EP 22787835 A 20220214

Priority
• JP 2021069993 A 20210416
• JP 2022005669 W 20220214

Abstract (en)
This panel production device comprises: a transport unit that transports, in a transport direction, a panel having a core member that includes a thermoplastic resin and is formed in a corrugated shape, and a first face plate that includes a thermoplastic resin, is formed in a plate shape, and is joined to one side surface of the core member; a supply unit that supplies a second face plate, which includes a thermoplastic resin and is formed in a plate shape, toward the other side surface of the core member; a heating unit for heating at least one surface among the surfaces at which the core member and the second face plate face each other; and a pressure application unit for applying pressure to the core member of the panel and the second face plate to fuse these components.

IPC 8 full level
B29D 7/00 (2006.01)

CPC (source: EP US)
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Designated contracting state (EPC)
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